



# STPS1L40A/U

## LOW DROP POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	1 A
$V_{RRM}$	40 V
$T_j(\text{max})$	150 °C
$V_F(\text{max})$	0.42 V

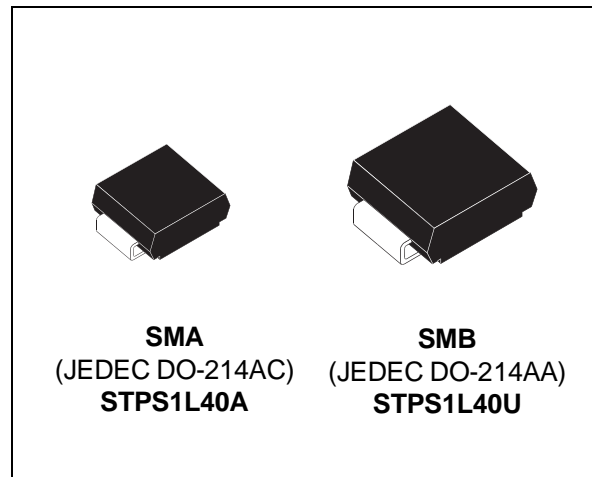
### FEATURES AND BENEFITS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP
- SURFACE MOUNT MINIATURE PACKAGE

### DESCRIPTION

Single chip Schottky rectifiers suited to Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in SMA and SMB, this device is especially intended for surface mounting and used in low voltage, high frequency inverters, free wheeling and polarity protection applications.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	40	V
$I_{F(RMS)}$	RMS forward current	8	A
$I_{F(AV)}$	Average forward current	$T_L = 130^\circ\text{C} \delta = 0.5$ 1	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms}$ Sinusoidal 60	A
$I_{RRM}$	Repetitive peak reverse current	$t_p = 2 \mu\text{s}$ square $F=1\text{kHz}$ 1	A
$I_{RSM}$	Non repetitive peak reverse current	$t_p = 100 \mu\text{s}$ square 1	A
$T_{stg}$	Storage temperature range	- 65 to + 150	°C
$T_j$	Maximum operating junction temperature *	150	°C
$dV/dt$	Critical rate of rise of reverse voltage	10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  thermal runaway condition for a diode on its own heatsink

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## THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	30	$^{\circ}\text{C/W}$
		SMB	25	

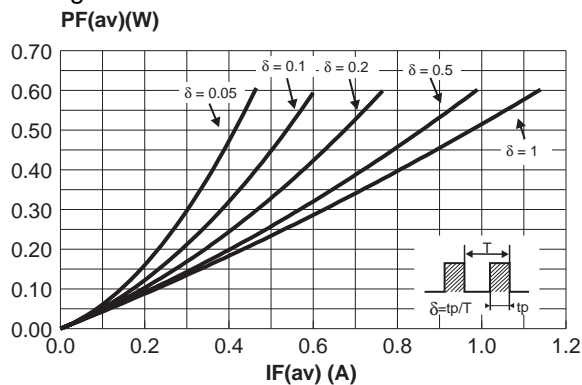
## STATIC ELECTRICAL CHARACTERISTICS

Symbol	Tests Conditions	Tests Conditions	Min.	Typ.	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = 40\text{ V}$		35	$\mu\text{A}$
		$T_j = 125^{\circ}\text{C}$		6	10	$\text{mA}$
$V_F^*$	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 1\text{ A}$		0.5	$\text{V}$
		$T_j = 125^{\circ}\text{C}$		0.37	0.42	
		$T_j = 25^{\circ}\text{C}$	$I_F = 2\text{ A}$		0.63	
		$T_j = 125^{\circ}\text{C}$		0.5	0.61	

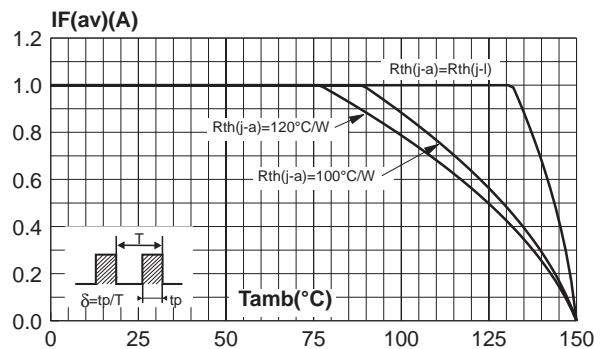
Pulse test : \*  $t_p = 380\ \mu\text{s}$ ,  $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation :  
 $P = 0.23 \times I_{F(AV)} + 0.19 I_{F(RMS)}^2$

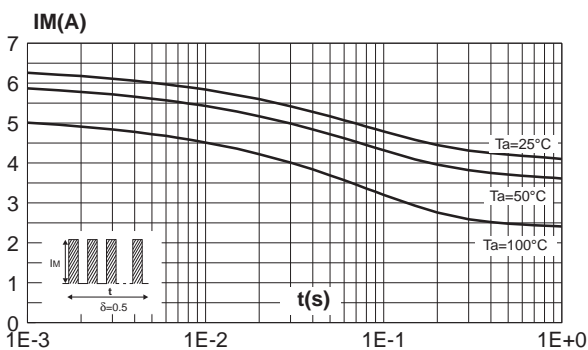
**Fig. 1:** Average forward power dissipation versus average forward current.



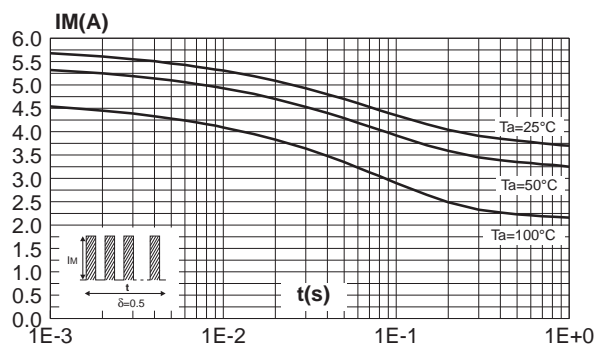
**Fig. 2:** Average forward current versus ambient temperature ( $\delta=0.5$ ).



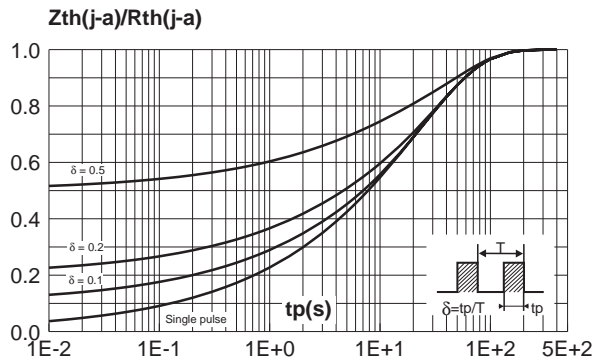
**Fig. 3-1:** Non repetitive surge peak forward current versus overload duration (maximum values) (SMB).



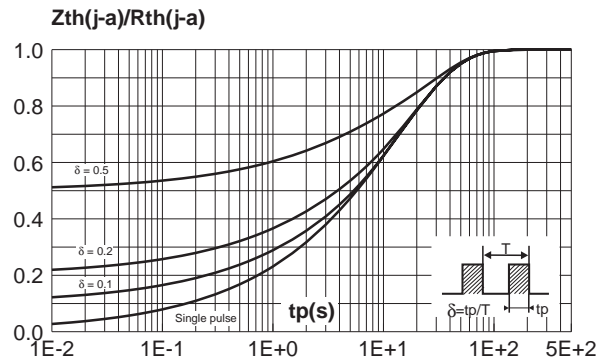
**Fig. 3-2:** Non repetitive surge peak forward current versus overload duration (maximum values) (SMA).



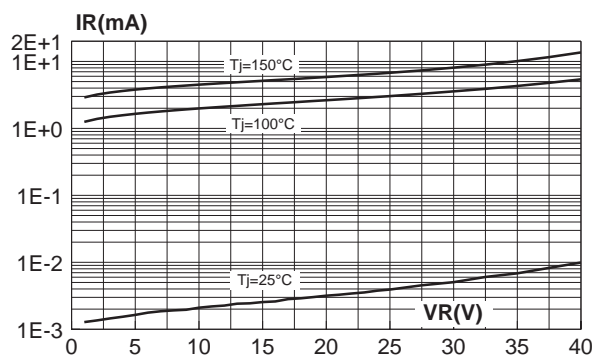
**Fig. 4-1:** Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy printed circuit board,  $e(\text{Cu})=35\mu\text{m}$ , recommended pad layout) (SMB).



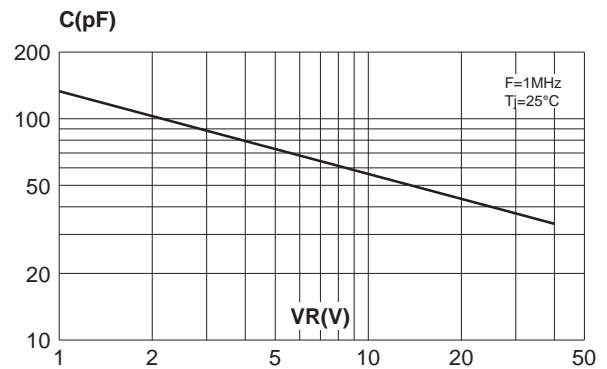
**Fig. 4-2:** Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy printed circuit board,  $e(\text{Cu})=35\mu\text{m}$ , recommended pad layout) (SMA).



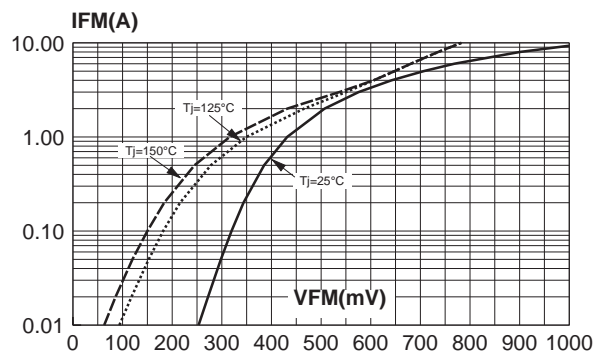
**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values).



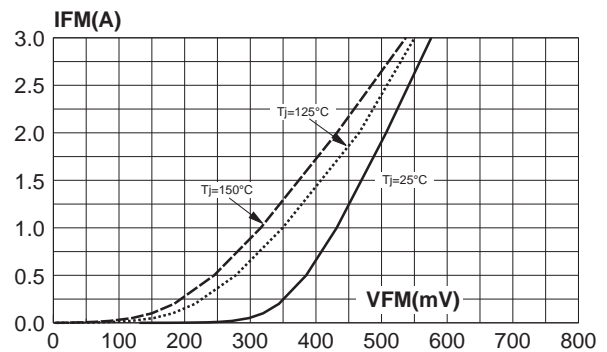
**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values).



**Fig. 7-1:** Forward voltage drop versus forward current (typical values, high level).

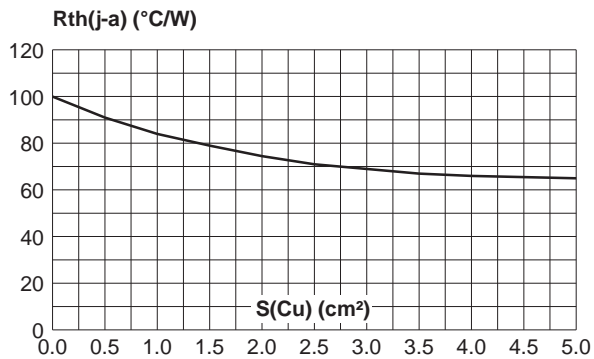


**Fig. 7-2:** Forward voltage drop versus forward current (typical values, low level).

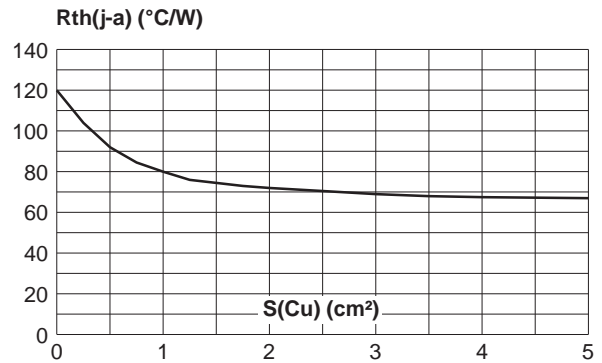


## STPS1L40A/U

**Fig. 8-1:** Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness  $e(\text{Cu})=35\mu\text{m}$ ) (SMB).

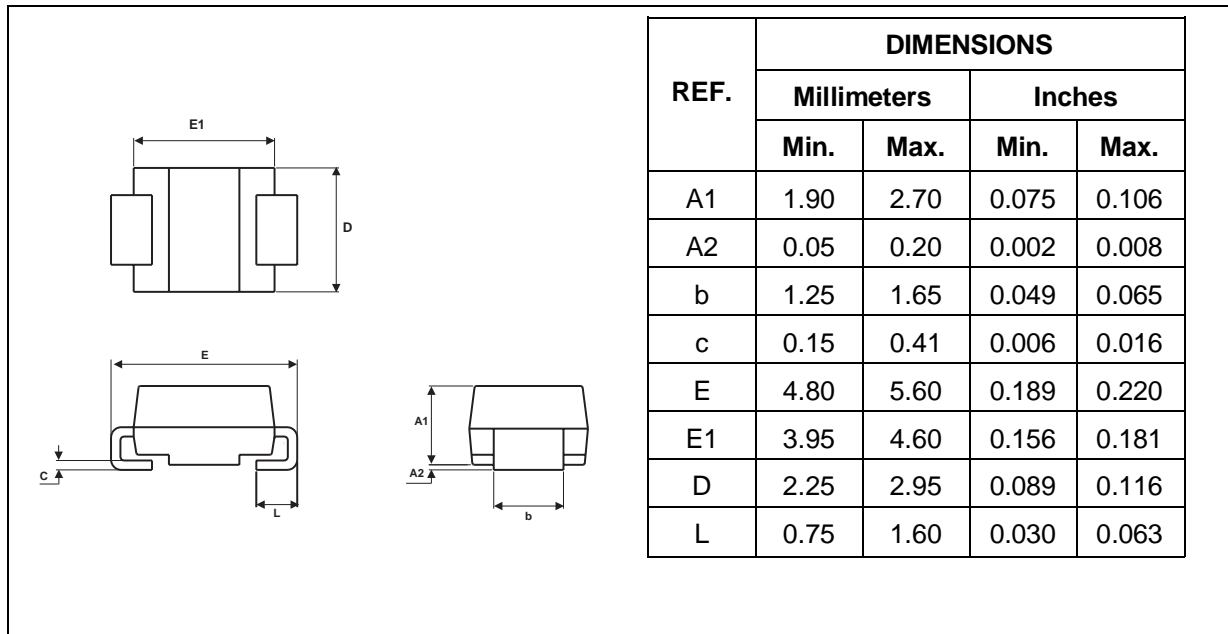


**Fig. 8-2:** Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness  $e(\text{Cu})=35\mu\text{m}$ ) (SMA).

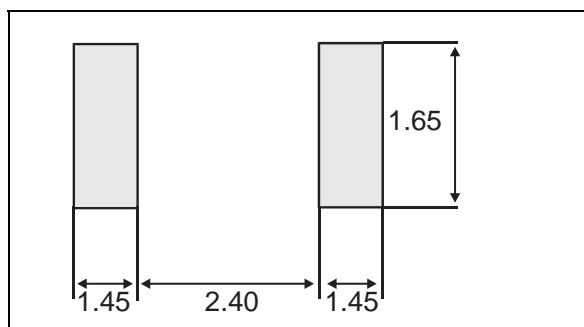


## PACKAGE MECHANICAL DATA

### SMA



### FOOT PRINT DIMENSIONS (in millimeters)

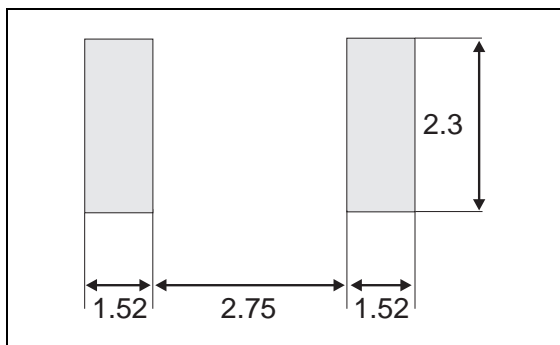


## PACKAGE MECHANICAL DATA

## SMB

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.41	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.60	0.030	0.063

## FOOT PRINT DIMENSIONS (in millimeters)



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS1L40U	GC4	SMB	0.107g	2500	Tape & reel
STPS1L40A	GB4	SMA	0.068g	5000	Tape & reel

- Band indicates cathode
- Epoxy meets UL94,V0

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